

# Fusion of Light Field and Photometric Stereo

High precision 3D reconstruction

D. Antensteiner



### HIGHLY PRECISE 3D RECONSTRUCTION

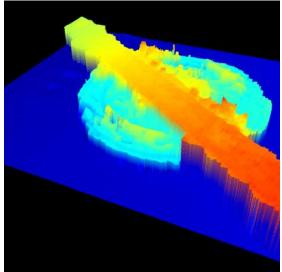
For objects with different surface properties (matt, glossy, textureless, ... )

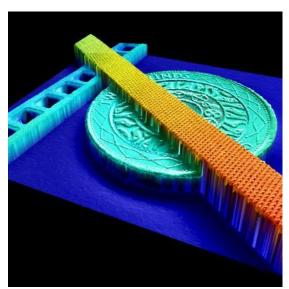
The scene (black zip tie, coin, file)

3D reconstruction using conventional stereo

3D reconstruction using light field and photometric stereo

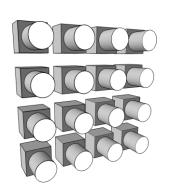








### SYNTHESIS OF LIGHT FIELDS & PHOTOMETRIC STEREO

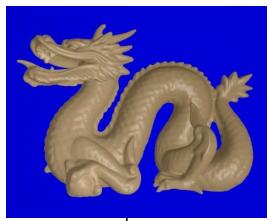


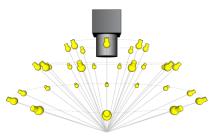
Absolute depth (+) Low depth detail (-)

Light field varying viewing angles

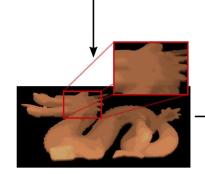


Photometric stereo varying illumination angles

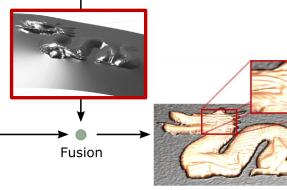




Absolute depth (-) High depth detail (+)



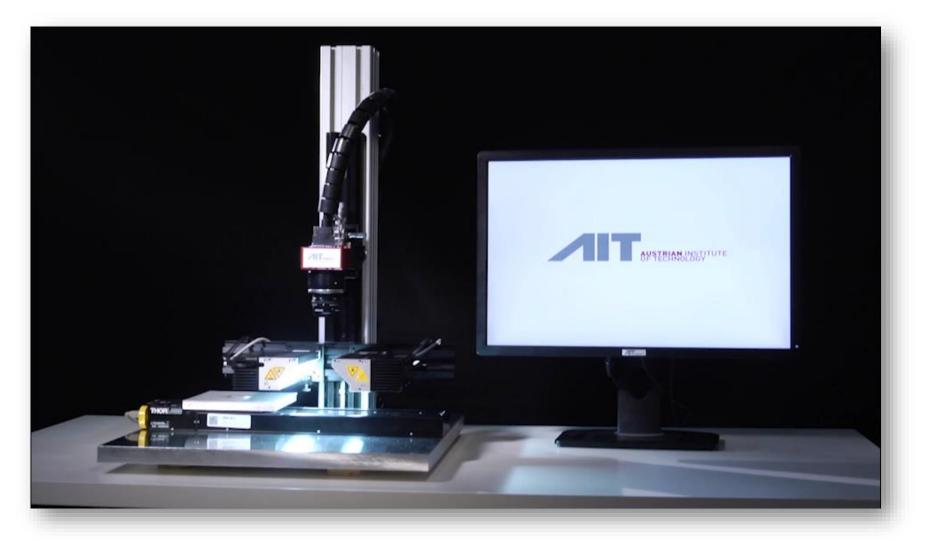
Lightfield depth



Lightfield + Photometric Stereo depth



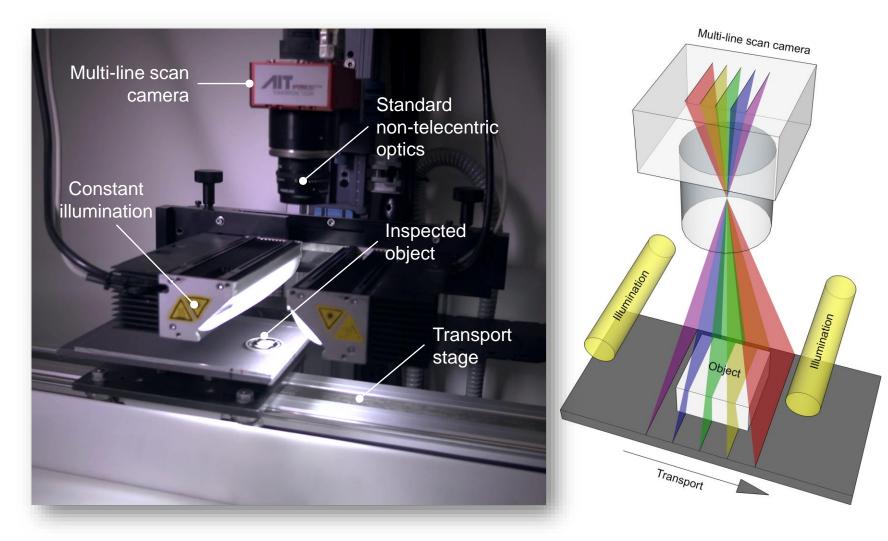
#### **CHALLENGE:** INLINE APPLICABILITY



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### AIT INLINE COMPUTATIONAL IMAGING



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### MULTIPLE VIEWING & ILLUMINATION ANGLES

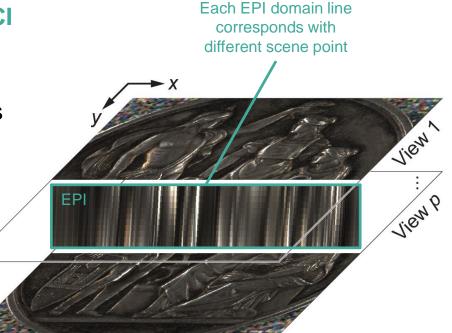




### DEPTH FROM LIGHT FIELD USING AIT ICI

- Multiple views obtained by AIT ICI form a 3D light field of the scene
- As usual in light field imaging, individual scene points map to lines in the EPI domain
- In AIT ICI, slopes of these lines have linear relationship with depth (due to semi-telecentry in the transport direction)
- 3D geometry of the scene can be inferred via multi-view correspondence analysis

(depth resolution limited due to small baseline)



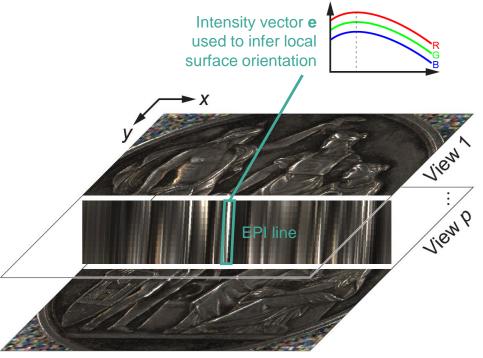
Transport direction  $\rightarrow$ 

Absolute depth(+) Low depth detail (-)



### PHOTOMETRIC STEREO USING AIT ICI

- Each light field view contains a different illumination
- Photometric information associated with a single scene point occur along corresponding EPI line
- To extract this information, an approximate depth model is necessary (previously obtained from light field)



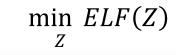
Transport direction  $\rightarrow$ 

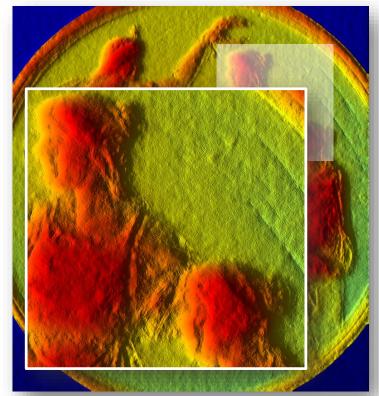
Absolute depth (-) High depth detail (+)



## **FUSION**

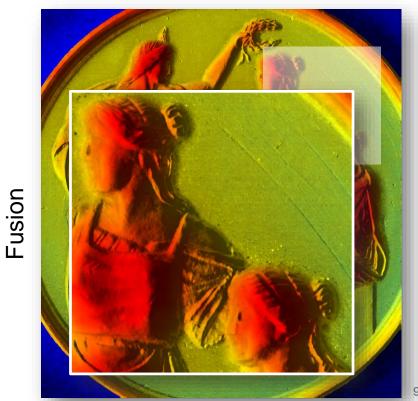
- Optimization problem •
- Objective split into two components •





Light field term  $E_{LF}$ Photometric stereo term  $E_{PS}$ 

$$\min_{Z} E_{LF}(Z) + E_{PS}(Z)$$



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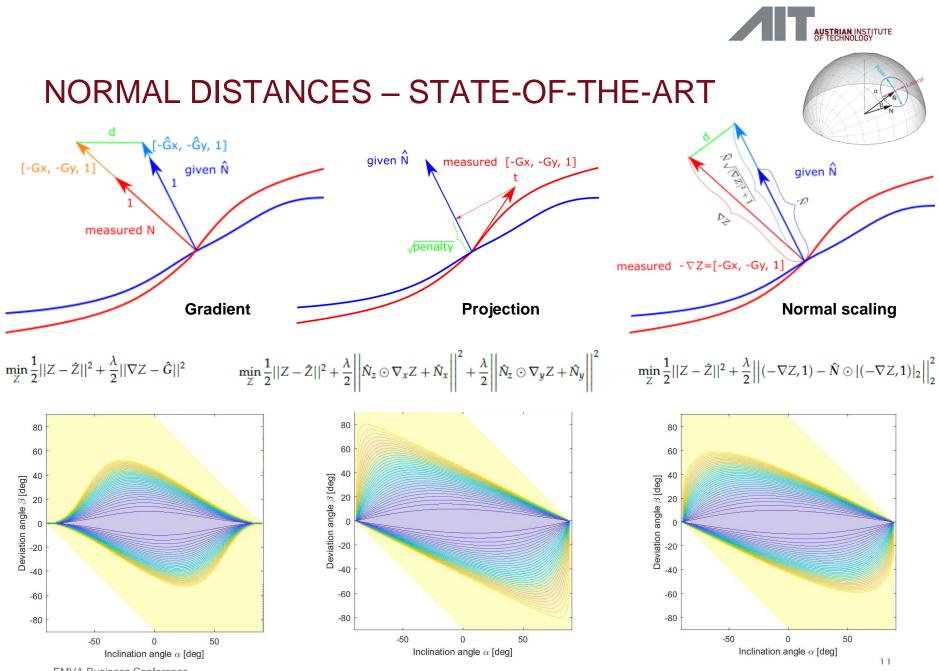
Light field only



Ideal PS error term

### NORMAL DISTANCES FOR PHOTOMETRIC STEREO

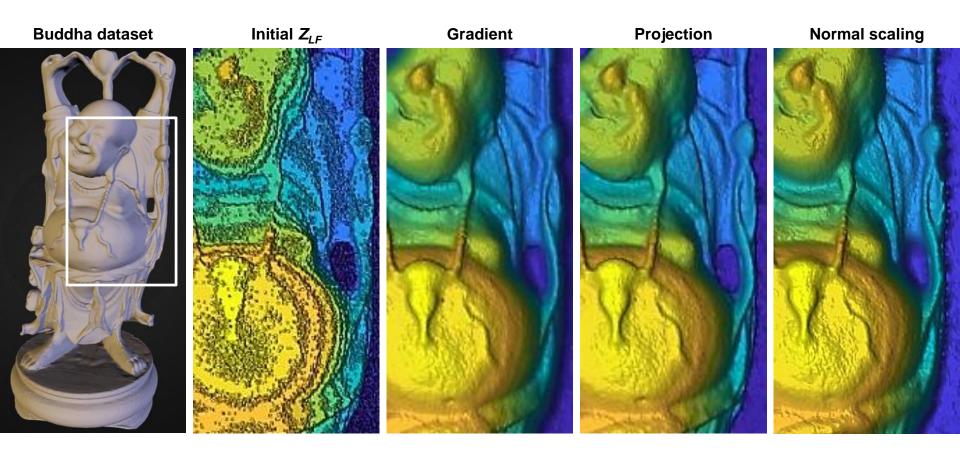
(hard to optimize) Geodesic 80 60 Deviation angle  $\beta$  [deg] -40 α -60 -80 -50 0 50 Inclination angle  $\alpha$  [deg]



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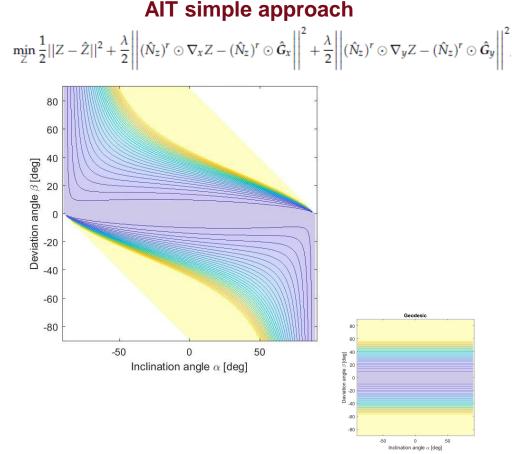


### LF + PS FUSION – STATE-OF-THE-ART





### NORMAL DISTANCES – AIT APPROACHES



## Compare with the ideal PS error term

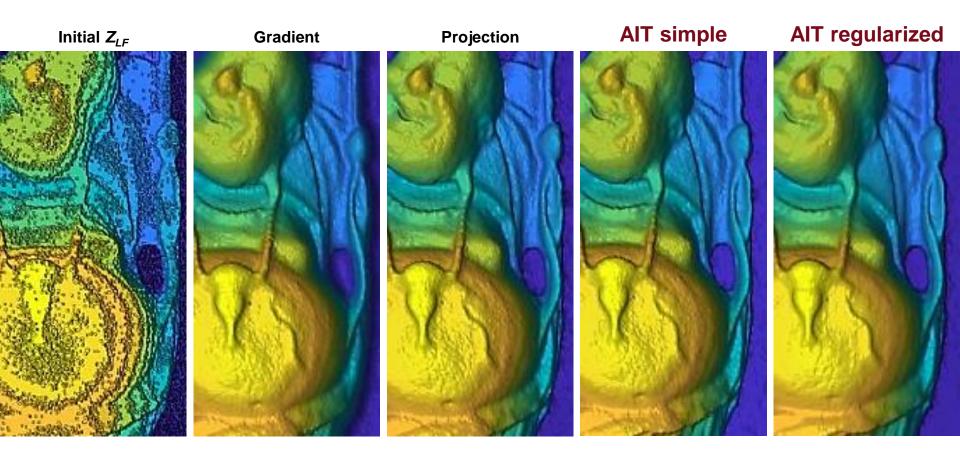
#### AIT TGV regularizer approach

 $\min_{Z,G} \alpha_1 ||\nabla Z - G||_{2,1} + \alpha_0 ||\nabla G||_{2,1} + \frac{\alpha}{2} ||Z - \hat{Z}||^2 + \frac{\beta}{2} ||G - \hat{G}||^2,$ 

- Advanced regularization approach using more complex prior
- Accurate yet fast method
- Preserve depth discontinuities
- Minimize staircasing artefacts of other state-ofthe-art regularizers

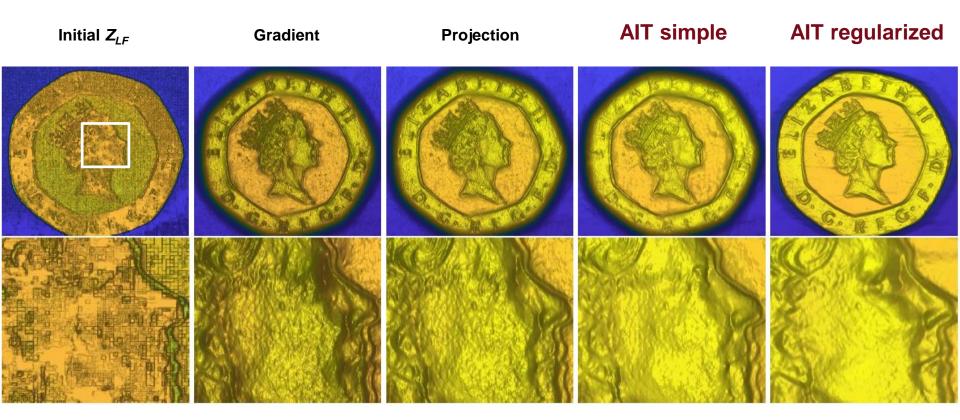


### LF + PS FUSION – AIT APPROACHES





### LF + PS FUSION – AIT APPROACHES





#### **EVALUATION**

MSE to the ground truth (Stanford object dataset)

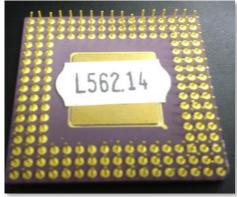
N

	Method Dataset	Ź	Surface orientation only	Gradient based	Projection	Normal Scaling	Ours	Ours with TGV
Depth [ <i>MSE</i> <sub>Z</sub> ]	Armadillo	4.23	34.05	2.04	0.13	2.01	0.10	0.19
	Buddha	4.85	117.29	2.12	0.15	1.60	0.12	0.22
	Dragon	4.60	48.71	1.94	0.13	1.75	0.10	0.18
	Avg.	4.53	66.68	1.53	0.14	1.79	0.11	0.20
Normals [ <i>GEO<sub>N</sub></i> ]	Armadillo	0.8226	0.2776	0.3205	0.2941	0.3474	0.2849	0.0664
	Buddha	0.8767	0.1922	0.2339	0.2102	0.2579	0.2013	0.0668
	Dragon	0.8611	0.2397	0.2805	0.2553	0.3094	0.2464	0.0666
	Avg.	0.8535	0.2365	0.2783	0.2532	0.3049	0.2442	0.0666
	Depth map							
	Error map EMVA Business Conference, Dubrovnik June 2018							



### CHIP - INLINE 3D + 2D INSPECTION

Sample part CHIP



Light field image stack

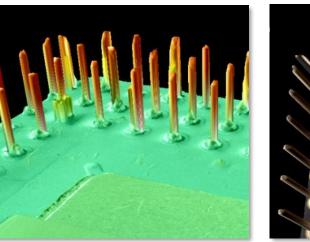
ICI 3D Modell (pseudo color map)



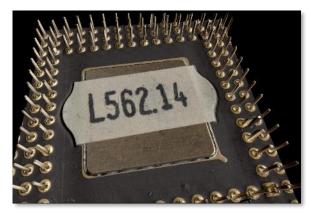
Detail



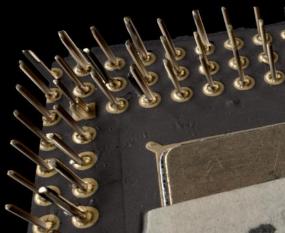
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ICI 3D Model + Texture



Detail





### FIELDS OF APPLICATION FOR ICI

Specifically developed for high-performance inline inspection

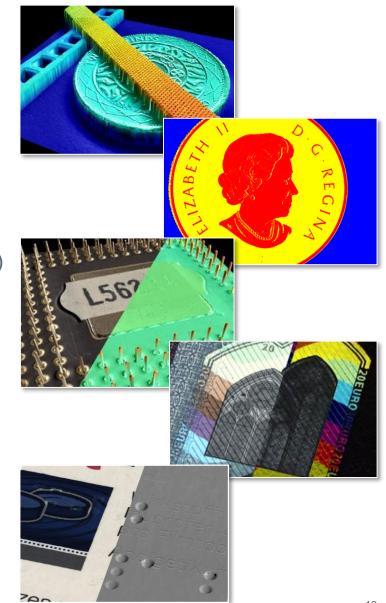
INDUSTRIAL INSPECTION	ELECTRONIC PARTS	METAL PARTS	PRINT INSPECTION
<ul> <li>2D and 3D features</li> <li>for challenging objects</li> <li>bright / dark</li> <li>matt / glossy</li> <li>texture-less</li> </ul>	<ul> <li>PCB and PCB assembly</li> <li>solder joints</li> <li>pin position and height</li> <li>etc.</li> </ul>	<ul> <li>3D geometry</li> <li>surface quality</li> <li>detection of pores, cracks, scratches,</li> <li>µm defects</li> </ul>	<ul> <li>printed matter</li> <li>embossing (e.g. braille)</li> <li>security features (e.g. holograms)</li> <li>tactile elements</li> </ul>



### **Industrial Application**

#### **AIT Inline Computational Imaging**

- Single multi-line scan camera with constant illumination (low system complexity, low cost)
- Suitable for high-speed inline applications (works with AIT xposure at 100 kHz)
- Suitable for high-resolution (currently 2-50 µm/px)
- High depth accuracy and detail (using light field and photometric stereo, equivalent lateral and depth resolution)
- Extremely flexible (speed vs. accuracy, image enhancement, color, 2D/3D, etc.)
- Future proof (extensible by new technologies beyond light field and photometric stereo)
- World-wide novel technology





# THANK YOU!

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